L Number	Hits	Search Text	DB	Time stamp
-	335	73/818.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/29 14:29
-	20244	(((lead wire cable strand) near6 (pull$4 push$4 test$4 monitor$4 observ$4 sens$4 detect$4 determin$4) near4 (adhes$4 adher$4 join$4 weld$4 fix$4 secur$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 15:50
-	16023	((((lead wire cable strand) near6 (pull$4 push$4 test$4 monitor$4 observ$4 sens$4 detect$4 determin$4) near4 (adhes$4 adher$4 join$4 weld$4 fix$4 secur$4))) and (housing cas$4 body packag$4 structure mount$4 backing assembl$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 15:44
-	8993	((((lead wire cable strand) near6 (pull$4 push$4 test$4 monitor$4 observ$4 sens$4 detect$4 determin$4) near4 (adhes$4 adher$4 join$4 weld$4 fix$4 secur$4))) same (housing cas$4 body packag$4 structure mount$4 backing assembl$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 15:48
-	15971	((((lead wire cable strand) near6 (pull$4 push$4 test$4 monitor$4 observ$4 sens$4 detect$4 determin$4) near4 (adhes$4 adher$4 join$4 weld$4 fix$4 secur$4))) and (housing case casing body packag$4 structure mount$4 backing assembl$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 15:50
-	375	(((((lead wire cable strand) near6 (pull$4 push$4 test$4 monitor$4 observ$4 sens$4 detect$4 determin$4) near4 (adhes$4 adher$4 join$4 weld$4 fix$4 secur$4))) same (housing cas$4 body packag$4 structure mount$4 backing assembl$4)) and 73/$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 15:50
-	719	(((((lead wire cable strand) near6 (pull$4 push$4 test$4 monitor$4 observ$4 sens$4 detect$4 determin$4) near4 (adhes$4 adher$4 join$4 weld$4 fix$4 secur$4))) and (housing case casing body packag$4 structure mount$4 backing assembl$4)) and 73/$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/07 15:50
-	77	((((((lead wire cable strand) near6 (pull$4 push$4 test$4 monitor$4 observ$4 sens$4 detect$4 determin$4) near4 (adhes$4 adher$4 join$4 weld$4 fix$4 secur$4))) same (housing cas$4 body packag$4 structure mount$4 backing assembl$4)) and 73/$6.ccls.) and ceramic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/08 14:34
-	144	((((((lead wire cable strand) near6 (pull$4 push$4 test$4 monitor$4 observ$4 sens$4 detect$4 determin$4) near4 (adhes$4 adher$4 join$4 weld$4 fix$4 secur$4))) and (housing case casing body packag$4 structure mount$4 backing assembl$4)) and 73/$6.ccls.) and ceramic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/08 16:20
-	0	((((((lead wire cable strand) near6 (test$4 monitor$4 observ$4 sens$4 detect$4 determin$4) near4 (adhes$4 adher$4 join$4 weld$4 fix$4 secur$4) near6 (pull$4 push$4))) same (housing cas$4 body packag$4 structure mount$4 backing assembl$4) same ceramic)) and 73/$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/08 17:28
-	2	((((((lead wire cable strand) near6 (test$4 monitor$4 observ$4 sens$4 detect$4 determin$4) near4 (adhes$4 adher$4 join$4 weld$4 fix$4 secur$4) near6 (pull$4 push$4))) same (housing casse casing body packag$4 structure mount$4 backing assembl$4) same ceramic))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/08 15:04
-	6	((((((lead wire cable strand) near6 (test$4 monitor$4 observ$4 sens$4 detect$4 determin$4) near4 (adhes$4 adher$4 join$4 force strength resist$4 weld$4 fix$4 secur$4) near6 (pull$4 push$4))) same (housing casse casing body packag$4 structure mount$4 backing assembl$4) same ceramic))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/08 16:46

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-		33	((lead wire cable strand) near6 (test$4 monitor$4 observ$4 sens$4 detect$4 determin$4) near4 (adhes$4 adher$4 join$4 force strength resist$4 weld$4 fix$4 secur$4) near6 (pull$4 tesnion$4 break$4 push$4)) and ((ceramic) near4 (housing case casing body packag$4 structure mount$4 backing assembl$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/08 16:01
-		130	((lead wire cable strand) near6 (test$4 monitor$4 observ$4 sens$4 detect$4 determin$4) near4 (adhes$4 adher$4 join$4 force strength resist$4 weld$4 fix$4 secur$4) near6 (pull$4 tension$4 break$4 push$4)) and 73/$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/08 16:18
-		35	((lead wire cable strand) near6 (test$4 monitor$4 observ$4 sens$4 detect$4 determin$4) near4 (bond$4) near6 (pull$4 tension$4 break$4 push$4)) and 73/$6.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/08 16:28
-		150	(((((lead wire cable strand) near6 (pull$4 push$4 test$4 monitor$4 observ$4 sens$4 detect$4 determin$4) near4 (bond$4))) and (housing case casing body packag$4 structure mount$4 backing assembl$4)) and 73/$6.ccls.) and ceramic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/08 16:29
-		0	((lead wire cable strand) near6 (test$4 monitor$4 observ$4 sens$4 detect$4 determin$4) near4 (adhes$4 adher$4 join$4 force strength resist$4 weld$4 fix$4 secur$4) near6 (pull$4 push$4)) same (clamp$4 grip$4) same ceramic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/08 16:53
-		0	((lead wire cable strand) near6 (test$4 monitor$4 observ$4 sens$4 detect$4 determin$4) near4 (adhes$4 adher$4 join$4 force strength bond$4 resist$4 weld$4 fix$4 secur$4) near6 (pull$4 push$4)) same (clamp$4 grip$4) same ceramic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/08 17:01
-		74	((lead wire cable strand) near6 (test$4 monitor$4 observ$4 sens$4 detect$4 determin$4) near4 (adhes$4 adher$4 join$4 force strength bond$4 resist$4 weld$4 fix$4 secur$4) near6 (pull$4 push$4)) same (clamp$4 grip$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/29 13:10
-		209	73/827.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/29 14:29
-		81	73/830.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/29 14:29
-		122	73/834.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/29 14:29
-		3573	((lead wire cable strand) near6 (test$4 monitor$4 observ$4 sens$4 detect$4 determin$4) near6 (pull$4 push$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 17:52
-		31	(73/827.ccls. 73/830.ccls. 73/834.ccls.) and ((lead wire cable strand) near6 (test$4 monitor$4 observ$4 sens$4 detect$4 determin$4) near6 (pull$4 push$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/08 17:33

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-	103	((lead wire cable strand) near6 (test$4 monitor$4 observ$4 sens$4 detect$4 determin$4) near6 (pull$4 push$4)) and (bolt$4 near8 nut)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 17:58
-	111	((lead wire cable bond$4 strand) near6 (test$4 monitor$4 observ$4 sens$4 detect$4 determin$4) near6 (pull$4 push$4)) and (bolt$4 near8 nut)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 17:58
-	10	("5085084" "6230569" "4677370" "5753823" "5836071").pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/09 19:40
-	5	("5085084" "6230569" "4677370" "5753823" "5836071").pn.	USPAT	2003/04/09 19:40
-	361	((lead wire cable strand) near6 (test$4 monitor$4 observ$4 asses$4 measur$4 meter$4 sens$4 detect$4 determin$4) near4 (adhes$4 adher$4 join$4 force strength bond$4 resist$4 weld$4 fix$4 secur$4) near6 (pull$4 push$4 force load$4)) and ((clamp$4 hold$4 secur$4 grip$4) near4 (base package board substrate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/29 14:21
-	15	(((lead wire cable strand) near6 (test$4 monitor$4 observ$4 asses$4 measur$4 meter$4 sens$4 detect$4 determin$4) near4 (adhes$4 adher$4 join$4 force strength bond$4 resist$4 weld$4 fix$4 secur$4) near6 (pull$4 push$4 force load$4)) and ((clamp$4 hold$4 secur$4 grip$4) near4 (base package board substrate))) and braz$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/29 14:22
-	346	73/818.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/29 14:37
-	216	73/827.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/29 14:29
-	83	73/830.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/29 14:29
-	123	73/834.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/29 14:29
-	13	(73/818.ccls. 73/827.ccls. 73/830.ccls. 73/834.ccls.) and (((lead wire cable strand) near6 (test$4 monitor$4 observ$4 asses$4 measur$4 meter$4 sens$4 detect$4 determin$4) near4 (adhes$4 adher$4 join$4 force strength bond$4 resist$4 weld$4 fix$4 secur$4) near6 (pull$4 push$4 force load$4)) and ((clamp$4 hold$4 secur$4 grip$4) near4 (base package board substrate)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/29 14:38

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